

* * * * * Welcome to STN International * * * * *

NEWS 1 Web Page URLs for STN Seminar Schedule - N. America
NEWS 2 "Ask CAS" for self-help around the clock
NEWS 3 SEP 09 CA/CAPLUS records now contain indexing from 1907 to the present
NEWS 4 Jul 15 Data from 1960-1976 added to RDISCLOSURE
NEWS 5 Jul 21 Identification of STN records implemented
NEWS 6 Jul 21 Polymer class term count added to REGISTRY
NEWS 7 Jul 22 INPADOC: Basic index (/BI) enhanced; Simultaneous Left and Right Truncation available
NEWS 8 AUG 05 New pricing for EUROPATFULL and PCTFULL effective August 1, 2003
NEWS 9 AUG 13 Field Availability (/FA) field enhanced in BEILSTEIN
NEWS 10 AUG 15 PATDPAFULL: one FREE connect hour, per account, in September 2003
NEWS 11 AUG 15 PCTGEN: one FREE connect hour, per account, in September 2003
NEWS 12 AUG 15 RDISCLOSURE: one FREE connect hour, per account, in September 2003
NEWS 13 AUG 15 TEMA: one FREE connect hour, per account, in September 2003
NEWS 14 AUG 18 Data available for download as a PDF in RDISCLOSURE
NEWS 15 AUG 18 Simultaneous left and right truncation added to PASCAL
NEWS 16 AUG 18 FROSTI and KOSMET enhanced with Simultaneous Left and Right Truncation
NEWS 17 AUG 18 Simultaneous left and right truncation added to ANABSTR
NEWS 18 SEP 22 DIPPR file reloaded
NEWS 19 SEP 25 INPADOC: Legal Status data to be reloaded
NEWS 20 SEP 29 DISSABS now available on STN

NEWS EXPRESS OCTOBER 01 CURRENT WINDOWS VERSION IS V6.01a, CURRENT MACINTOSH VERSION IS V6.0b(ENG) AND V6.0Jb(JP), AND CURRENT DISCOVER FILE IS DATED 23 SEPTEMBER 2003
NEWS HOURS STN Operating Hours Plus Help Desk Availability
NEWS INTER General Internet Information
NEWS LOGIN Welcome Banner and News Items
NEWS PHONE Direct Dial and Telecommunication Network Access to STN
NEWS WWW CAS World Wide Web Site (general information)

Enter NEWS followed by the item number or name to see news on that specific topic.

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* * * * * STN Columbus * * * * *

FILE 'HOME' ENTERED AT 15:39:05 ON 06 OCT 2003

=> file inspec

COST IN U.S. DOLLARS

SINCE FILE	TOTAL
ENTRY	SESSION
0.21	0.21

FULL ESTIMATED COST

FILE 'INSPEC' ENTERED AT 15:39:12 ON 06 OCT 2003

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FILE LAST UPDATED: 6 OCT 2003 <20031006/UP>
FILE COVERS 1969 TO DATE.

<<< SIMULTANEOUS LEFT AND RIGHT TRUNCATION AVAILABLE IN
THE BASIC INDEX >>>

=> s diffusion bonding
194656 DIFFUSION
47403 BONDING
L1 739 DIFFUSION BONDING
(DIFFUSION(W) BONDING)

=> s aluminum
L2 42383 ALUMINUM

=> s l1 and l2
L3 43 L1 AND L2

=> s grain or grains
98578 GRAIN
39630 GRAINS
L4 116958 GRAIN OR GRAINS

=> s l3 and l4
L5 8 L3 AND L4

=> d l5 1-8

L5 ANSWER 1 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	Cited References
--------------	---------------------

AN 2003:7507088 INSPEC DN A2003-04-8120G-026
TI Multi-sheet structures in 7475 **aluminum** by friction stir welding in
concert with post-weld superplastic forming.
AU Charit, I.; Mishra, R.S. (Dept. of Metall. Eng., Missouri Univ., Rolla,
MO, USA); Mahoney, M.W.
SO Scripta Materialia (1 Nov. 2002) vol.47, no.9, p.631-6. 11 refs.
Doc. No.: S1359-6462(02)00257-9
Published by: Elsevier for Board of Directors of Acta Metall
Price: CCCC 1359-6462/02/\$22.00
CODEN: SCRMBU ISSN: 1359-6462
SICI: 1359-6462(20021101)47:9L.631:MSS7;1-N
DT Journal
TC Experimental
CY United States
LA English

L5 ANSWER 2 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	Cited References
--------------	---------------------

AN 2002:7444428 INSPEC DN A2002-24-8120G-042
TI The effect of processing variables on the structure and chemistry of
Ti-aluminide based LMCS.
AU Goda, D.J.; Richards, N.L. (Dept. of Mech. & Ind. Eng., Manitoba Univ.,
Winnipeg, Man., Canada); Caley, W.F.; Chaturvedi, M.C.
SO Materials Science & Engineering A (Structural Materials: Properties,
Microstructure and Processing) (Sept. 2002) vol.A334, no.1-2, p.280-90. 16
refs.

Doc. No.: S0921-5093(01)01894-9
 Published by: Elsevier
 Price: CCCC 0921-5093/02/\$22.00
 CODEN: MSAPE3 ISSN: 0921-5093
 SICI: 0921-5093(200209)A334:1/2L.280:EPVS;1-#

DT Journal
 TC Experimental
 CY Switzerland
 LA English

L5 ANSWER 3 OF 8 INSPEC (C) 2003 IEE on STN

Full Text String
 Text References

AN 2002:7334906 INSPEC DN A2002-17-6170N-004
 TI Investigation of copper segregation to the Sigma 5(310)/[001] symmetric tilt **grain** boundary in **aluminum**.
 AU Plitzko, J.M.; Campbell, G.H.; King, W.E. (Chem. & Mater. Sci. Directorate, Lawrence Livermore Nat. Lab., CA, USA); Foiles, S.M.
 SO Advances in Materials Problem Solving with the Electron Microscopy. Symposium (Materials Research Society Symposium Proceedings Vol.589) Editor(s): Bentley, J.; Allen, C.; Dahmen, U.; Petrov, I. Warrendale, PA, USA: Mater. Res. Soc., 2001. p.301-6 of xiii+406 pp. 13 refs.
 Conference: Boston, MA, USA, 30 Nov-3 Dec 1999
 ISBN: 1-55899-497-1
 DT Conference Article
 TC Experimental; Theoretical
 CY United States
 LA English

L5 ANSWER 4 OF 8 INSPEC (C) 2003 IEE on STN

Full Text String
 Text References

AN 1999:6171301 INSPEC DN A1999-07-8140N-012
 TI **Grain** morphology, texture, and microhardness gradients in **aluminum** diffusion-bonded to **aluminum** oxide.
 AU Lin, C.-T.; Shen, Y.-L. (Dept. of Mater. Sci. & Eng., MIT, Cambridge, MA, USA); Becker, R.; Suresh, S.
 SO Acta Materialia (15 Jan. 1999) vol.47, no.2, p.501-15. 36 refs.
 Doc. No.: S1359-6454(98)00361-9
 Published by: Elsevier
 Price: CCCC 1359-6454/99/\$19.00+0.00
 CODEN: AMATEB ISSN: 1359-6454
 SICI: 1359-6454(19990115)47:2L.501:GMTM;1-C
 DT Journal
 TC Experimental
 CY United Kingdom
 LA English

ORDERED

L5 ANSWER 5 OF 8 INSPEC (C) 2003 IEE on STN

Full Text String
 Text References

AN 1996:5487351 INSPEC DN A9705-6170N-011
 TI Sigma 5 (210)/[001] symmetric tilt **grain** boundary in yttrium **aluminum** garnet.
 AU Campbell, G.H. (Lawrence Livermore Nat. Lab., CA, USA)
 SO Journal of the American Ceramic Society (Nov. 1996) vol.79, no.11, p.2883-91. 24 refs.
 Published by: American Ceramic Soc
 Price: CCCC 0002-7820/96/\$5.00+.50

CODEN: JACTAW ISSN: 0002-7820
 SICI: 0002-7820(199611)79:11L;2883:(STG;1-O

DT Journal
 TC Theoretical; Experimental
 CY United States
 LA English

L5 ANSWER 6 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	References
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AN 1994:4815125 INSPEC DN A9424-8120G-007
 TI Investigation of bonding formation behavior during superplastic forming and **diffusion bonding** processing using conversion coating film.
 AU Iwasaki, H. (Dept. of Mater. Sci. & Eng., Himeji Inst. of Technol., Japan); Mori, T.; Nagano, T.; Higashi, K.; Tanimura, S.
 SO Journal of the Society of Materials Science, Japan (Oct. 1994) vol.43, no.493, p.1304-8. 14 refs.
 CODEN: ZARYAQ ISSN: 0514-5163
 DT Journal
 TC Experimental
 CY Japan
 LA Japanese

L5 ANSWER 7 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	References
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AN 1992:4249720 INSPEC DN A9221-8190-003
 TI **Diffusion bonding** of superplastic 7075 **aluminum** alloy.
 AU Huang Yan; Cui Jianzhong; Ma Longxiang (Dept. of Metalforming, Northeast Univ. of Technol., Shenyang, China)
 SO Superplasticity in Metals, Ceramics and Intermetallics Symposium
 Editor(s): Mayo, M.J.; Kobayashi, M.; Wadsworth, J.
 Pittsburgh, PA, USA: Mater. Res. Soc, 1990. p.149-54 of xi+401 pp. 4 refs.
 Conference: San Francisco, CA, USA, 16-19 April 1990
 DT Conference Article
 TC Experimental
 CY United States
 LA English

L5 ANSWER 8 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	References
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AN 1992:4249718 INSPEC DN A9221-8190-002
 TI Kinetics of **grain** growth across bond interface during **diffusion bonding**.
 AU Huang Yan; Cui Jianzhong; Ma Longxiang (Dept. of Metalforming, Northeast Univ. of Tech., Shenyang, China)
 SO Superplasticity in Metals, Ceramics and Intermetallics Symposium
 Editor(s): Mayo, M.J.; Kobayashi, M.; Wadsworth, J.
 Pittsburgh, PA, USA: Mater. Res. Soc, 1990. p.137-42 of xi+401 pp. 5 refs.
 Conference: San Francisco, CA, USA, 16-19 April 1990
 DT Conference Article
 TC Theoretical
 CY United States
 LA English

=> s aluminum

L6 42383 ALUMINUM

=> s 15 and 16

L7 8 L5 AND L6

=> d 17 1-2

L7 ANSWER 1 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	Citing References
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AN 2003:7507088 INSPEC DN A2003-04-8120G-026
 TI Multi-sheet structures in 7475 **aluminum** by friction stir welding in concert with post-weld superplastic forming.
 AU Charit, I.; Mishra, R.S. (Dept. of Metall. Eng., Missouri Univ., Rolla, MO, USA); Mahoney, M.W.
 SO Scripta Materialia (1 Nov. 2002) vol.47, no.9, p.631-6. 11 refs.
 Doc. No.: S1359-6462(02)00257-9
 Published by: Elsevier for Board of Directors of Acta Metall
 Price: CCCC 1359-6462/02/\$22.00
 CODEN: SCRMBU ISSN: 1359-6462
 SICI: 1359-6462(20021101)47:9L.631:MSS7;1-N
 DT Journal
 TC Experimental
 CY United States
 LA English

L7 ANSWER 2 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	Citing References
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AN 2002:7444428 INSPEC DN A2002-24-8120G-042
 TI The effect of processing variables on the structure and chemistry of Ti-aluminide based LMCS.
 AU Goda, D.J.; Richards, N.L. (Dept. of Mech. & Ind. Eng., Manitoba Univ., Winnipeg, Man., Canada); Caley, W.F.; Chaturvedi, M.C.
 SO Materials Science & Engineering A (Structural Materials: Properties, Microstructure and Processing) (Sept. 2002) vol.A334, no.1-2, p.280-90. 16 refs.
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 Published by: Elsevier
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 CODEN: MSAPE3 ISSN: 0921-5093
 SICI: 0921-5093(200209)A334:1/2L.280:EPVS;1-#
 DT Journal
 TC Experimental
 CY Switzerland
 LA English

L7 ANSWER 3 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	Citing References
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AN 2002:7334906 INSPEC DN A2002-17-6170N-004
 TI Investigation of copper segregation to the Sigma 5(310)/[001] symmetric tilt **grain** boundary in **aluminum**.
 AU Plitzko, J.M.; Campbell, G.H.; King, W.E. (Chem. & Mater. Sci. Directorate, Lawrence Livermore Nat. Lab., CA, USA); Foiles, S.M.
 SO Advances in Materials Problem Solving with the Electron Microscopy. Symposium (Materials Research Society Symposium Proceedings Vol.589)
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 Warrendale, PA, USA: Mater. Res. Soc, 2001. p.301-6 of xiii+406 pp. 13 refs.
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 DT Conference Article

TC Experimental; Theoretical
CY United States
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AN 1999:6171301 INSPEC DN A1999-07-8140N-012
TI Grain morphology, texture, and microhardness gradients in aluminum diffusion-bonded to aluminum oxide.
AU Lin, C.-T.; Shen, Y.-L. (Dept. of Mater. Sci. & Eng., MIT, Cambridge, MA, USA); Becker, R.; Suresh, S.
SO Acta Materialia (15 Jan. 1999) vol.47, no.2, p.501-15. 36 refs.
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CODEN: AMATEB ISSN: 1359-6454
SICI: 1359-6454(19990115)47:2L:501:GMTM;1-C
DT Journal
TC Experimental
CY United Kingdom
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L7 ANSWER 5 OF 8 INSPEC (C) 2003 IEE on STN

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AN 1996:5487351 INSPEC DN A9705-6170N-011
TI Sigma 5 (210)/[001] symmetric tilt grain boundary in yttrium aluminum garnet.
AU Campbell, G.H. (Lawrence Livermore Nat. Lab., CA, USA)
SO Journal of the American Ceramic Society (Nov. 1996) vol.79, no.11, p.2883-91. 24 refs.
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L7 ANSWER 6 OF 8 INSPEC (C) 2003 IEE on STN

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AN 1994:4815125 INSPEC DN A9424-8120G-007
TI Investigation of bonding formation behavior during superplastic forming and diffusion bonding processing using conversion coating film.
AU Iwasaki, H. (Dept. of Mater. Sci. & Eng., Himeji Inst. of Technol., Japan); Mori, T.; Nagano, T.; Higashi, K.; Tanimura, S.
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AN 1992:4249720 INSPEC DN A9221-8190-003
 TI **Diffusion bonding** of superplastic 7075 **aluminum** alloy.
 AU Huang Yan; Cui Jianzhong; Ma Longxiang (Dept. of Metalforming, Northeast Univ. of Technol., Shenyang, China)
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L7 ANSWER 8 OF 8 INSPEC (C) 2003 IEE on STN



AN 1992:4249718 INSPEC DN A9221-8190-002
 TI Kinetics of **grain** growth across bond interface during **diffusion bonding**.
 AU Huang Yan; Cui Jianzhong; Ma Longxiang (Dept. of Metalforming, Northeast Univ. of Tech., Shenyang, China)
 SO Superplasticity in Metals, Ceramics and Intermetallics Symposium
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NEWS 5 Jul 21 Identification of STN records implemented
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NEWS 11 AUG 15 PCTGEN: one FREE connect hour, per account, in September 2003
NEWS 12 AUG 15 RDISCLOSURE: one FREE connect hour, per account, in September 2003
NEWS 13 AUG 15 TEMA: one FREE connect hour, per account, in September 2003
NEWS 14 AUG 18 Data available for download as a PDF in RDISCLOSURE
NEWS 15 AUG 18 Simultaneous left and right truncation added to PASCAL
NEWS 16 AUG 18 FROSTI and KOSMET enhanced with Simultaneous Left and Right Truncation
NEWS 17 AUG 18 Simultaneous left and right truncation added to ANABSTR
NEWS 18 SEP 22 DIPPR file reloaded
NEWS 19 SEP 25 INPADOC: Legal Status data to be reloaded
NEWS 20 SEP 29 DISSABS now available on STN

NEWS EXPRESS OCTOBER 01 CURRENT WINDOWS VERSION IS V6.01a, CURRENT MACINTOSH VERSION IS V6.0b(ENG) AND V6.0Jb(JP), AND CURRENT DISCOVER FILE IS DATED 23 SEPTEMBER 2003
NEWS HOURS STN Operating Hours Plus Help Desk Availability
NEWS INTER General Internet Information
NEWS LOGIN Welcome Banner and News Items
NEWS PHONE Direct Dial and Telecommunication Network Access to STN
NEWS WWW CAS World Wide Web Site (general information)

Enter NEWS followed by the item number or name to see news on that specific topic.

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* * * * * STN Columbus * * * * *

FILE 'HOME' ENTERED AT 15:22:04 ON 06 OCT 2003

=> file inspec

COST IN U.S. DOLLARS

SINCE FILE	TOTAL
ENTRY	SESSION
0.21	0.21

FULL ESTIMATED COST

FILE 'INSPEC' ENTERED AT 15:22:19 ON 06 OCT 2003

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FILE LAST UPDATED: 6 OCT 2003 <20031006/UP>
FILE COVERS 1969 TO DATE.

<<< SIMULTANEOUS LEFT AND RIGHT TRUNCATION AVAILABLE IN
THE BASIC INDEX >>>

=> s diffusion bonding
194656 DIFFUSION
47403 BONDING
L1 739 DIFFUSION BONDING
(DIFFUSION(W) BONDING)

=> s sputtering adj target
42407 SPUTTERING
53 ADJ
118084 TARGET
L2 0 SPUTTERING ADJ TARGET
(SPUTTERING(W) ADJ(W) TARGET)

=> s sputtering
L3 42407 SPUTTERING

=> s l1 and l3
L4 8 L1 AND L3

=> d l4 1-8

L4 ANSWER 1 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	Single References
--------------	----------------------

AN 2003:7747698 INSPEC DN A2003-22-6855-044
TI Sputter deposition and film characterization of NiAl on sapphire fibres.
AU Reichert, K.; Martinez, C.; Kyrsta, S.; Cremer, R.; Neuschutz, D. (Mater.
Chem., Rheinisch-Westfalische Tech. Hochschule, Aachen, Germany)
SO Vacuum (9 May 2003) vol.71, no.1-2, p.241-6. 13 refs.
Published by: Elsevier
Price: CCCC 0042-207X/03/\$30.00
CODEN: VACUAV ISSN: 0042-207X
SICI: 0042-207X(20030509)71:1/2L.241:SDFC;1-A
Conference: 9th Joint Vacuum Conference (JVC-9). Schloss Seggau, Austria,
16-20 June 2002
DT Conference Article; Journal
TC Experimental
CY United Kingdom
LA English

L4 ANSWER 2 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	Single References
--------------	----------------------

AN 2003:7667262 INSPEC DN A2003-15-8190-005
TI Improvement of **diffusion bonding** joint by Ar ion bombardment.
AU Airu Wang; Ohashi, O.; Aoki, M.; Yamaguchi, N. (Graduate Sch. of Sci. &
Technol., Niigata Univ., Japan)
SO Materials Science Forum (2003) vol.423-425, p.113-17. 12 refs.
Published by: Trans Tech Publications
CODEN: MSFOEP ISSN: 0255-5476
SICI: 0255-5476(2003)423/425L.113:IDBJ;1-H
Conference: Functionally Graded Materials VII. Seventh International

Symposium. Beijing, China, 15-18 Oct 2002

DT Conference Article; Journal
TC Experimental
CY Switzerland
LA English

L4 ANSWER 3 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	CITE References
--------------	--------------------

AN 2002:7336779 INSPEC DN A2002-17-8115G-017
TI Bonding between Cu and alpha -Al₂O₃.
AU Min Gao; Scheu, C.; Wagner, T.; Kurtz, W.; Ruhle, M. (Max-Planck-Inst. fur Metallforschung, Stuttgart, Germany)
SO Zeitschrift fur Metallkunde (May 2002) vol.93, no.5, p.438-43. 20 refs.
Published by: Carl Hanser GmbH
CODEN: ZEMTAE ISSN: 0044-3093
SICI: 0044-3093(200205)93:5L.438:BBA;1-P
DT Journal
TC Experimental
CY Germany, Federal Republic of
LA English

L4 ANSWER 4 OF 8 INSPEC (C) 2003 FIZ KARLSRUHE on STN

Full Text	CITE References
--------------	--------------------

AN 1999:6333551 INSPEC DN A1999-19-7450-015
TI Twist angle dependence of Josephson junction effect measured in the [001] twist boundary of Bi₂Sr₂CaCu₂O_x superconductor bicrystals.
AU Xu, B.S. (Tanaka Solid Junction Project, Japan Sci. & Technol. Corp., Yokohama, Japan); Ichinose, H.; Tanaka, S.
SO Materials Science Forum (1999) vol.294-296, p.263-8. 16 refs.
Published by: Trans Tech Publications
CODEN: MSFOEP ISSN: 0255-5476
SICI: 0255-5476(1999)294/296L.263:TADJ;1-5
Conference: Intergranular and Interphase Boundaries in Materials - iib98. 9th International Conference. Prague, Czech Republic, 6-9 July 1998
DT Conference Article; Journal
TC Experimental
CY Switzerland
LA English

L4 ANSWER 5 OF 8 INSPEC (C) 2003 FIZ KARLSRUHE on STN

Full Text	CITE References
--------------	--------------------

AN 1999:6144920 INSPEC DN A1999-05-2852-034
TI Assessment of tungsten for use in the ITER plasma facing components.
AU Davis, J.W. (Boeing Co., St. Louis, MO, USA); Barabash, V.R.; Makhankov, A.; Ploch, L.; Slattery, K.T.
SO Journal of Nuclear Materials (Oct. 1998) vol.258-263, pt.A, p.308-12. 10 refs.
Published by: Elsevier
Price: CCCC 0022-3115/98/\$19.00
CODEN: JNUMAM ISSN: 0022-3115
SICI: 0022-3115(199810)258/263:AL.308:ATIP;1-I
Conference: 8th International Conference on Fusion Reactor Materials (CFRM-8). Sendai, Japan, 26-31 Oct 1997
DT Conference Article; Journal
TC Experimental
CY Netherlands
LA English

L4 ANSWER 6 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	Citing References
--------------	----------------------

AN 1996:5289200 INSPEC DN A9614-8140N-019

TI The effects of metal coating on the **diffusion bonding** in Al₂O₃/Inconel 600 and the modulus of rupture strength of alumina.

AU Hwang, H.R.; Lee, R.Y. (Dept. of Mater. Sci. & Eng., Dankook Univ., South Korea)

SO Journal of Materials Science (1 May 1996) vol.31, no.9, p.2429-35. 20 refs.

Published by: Chapman & Hall

CODEN: JMTSAS ISSN: 0022-2461

SICI: 0022-2461(19960501)31:9L.2429:EMCD;1-L

DT Journal

TC Experimental

CY United Kingdom

LA English

L4 ANSWER 7 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	Citing References
--------------	----------------------

AN 1992:4079833 INSPEC DN A9205-7450-013; B9203-3240C-008

TI Artificial YBCO grain boundary junctions on SrTiO₃ and Si bicrystals.

AU Suzuki, H. (Riken Corp., Kumagaya, Japan); Kurosawa, H.; Chen, J.; Hirotsu, Y.; Nakajima, K.; Yamashita, T.; Myoren, H.; Osaka, Y.

SO Superconductor Science & Technology (Sept. 1991) vol.4, no.9, p.479-81. 13 refs.

Price: CCCC 0953-2048/91/090479+03\$03.50

ISSN: 0953-2048

Conference: Superconductive Electronics Conference. Strathclyde, UK, 25-27 June 1991

DT Conference Article; Journal

TC Experimental

CY United Kingdom

LA English

L4 ANSWER 8 OF 8 INSPEC (C) 2003 IEE on STN

Full Text	Citing References
--------------	----------------------

AN 1992:4062268 INSPEC DN A9204-7450-003

TI YBa₂Cu₃O₇-delta angle grain boundary junction on Si bicrystal substrate.

AU Chen, J. (Dept. of Electron., Nagaoka Univ. of Technol., Japan); Yamashita, T.; Suzuki, H.; Nakajima, K.; Kurosawa, H.; Mutoh, Y.; Hirotsu, Y.; Myoren, H.; Osaka, Y.

SO Japanese Journal of Applied Physics, Part 1 (Regular Papers & Short Notes) (Sept. 1991) vol.30, no.9A, p.1964-8. 32 refs.

CODEN: JAPNDE ISSN: 0021-4922

DT Journal

TC Experimental

CY Japan

LA English

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